| ABBOLIATION CONNECTING<br>LECTRONICS INDUSTRIES® INCLUSTRIES® | Bannockb   | urn, Illinois. A          | Il rights reserved untions. | under both           | This docume<br>level parts, t | ent is a decla  | ration of<br>on encom | the substance<br>passes all lov | es withi<br>ver leve            | n the manufactur<br>l materials for w | er listed i<br>hich the n | tem. No<br>nanufact | ote: if the<br>turer has | item is an ass<br>engineering re | embly with lower<br>esponsibility. |
|---|--|---------------------------|-----------------------------|----------------------|-------------------------------|---|-----------------------|---------------------------------|---------------------------------|---------------------------------------|---------------------------|---------------------|--------------------------|----------------------------------|------------------------------------|
|   | IPC Web Site for Information on IPC-1752 Standard Form Typ<br>http://www.ipc.org/IPC-175x Distribute |                           |                             |                      | e *                           | Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Mater |                       |                                 |                                 |                                       | als and Mfg Information   |                     |                          |                                  |                                    |
| Supplier Information  |  |                           |                             |                      |                               |   |                       |                                 |                                 |                                       |                           |                     |                          |                                  |                                    |
| Company name*   | Company unique ID  |                           |                             | Unique ID Authority  |                               |   |                       |                                 | Response Date*                  |                                       |                           |                     |                          |                                  |                                    |
| onsemi  |  |                           |                             |                      |                               |   |                       |                                 |                                 |                                       | 2024-05-09                |                     |                          |                                  |                                    |
| Contact Name  | ct I   |                           |                             | Phone - Contact*     |                               |   |                       |                                 | Email - Contact*                |                                       |                           |                     |                          |                                  |                                    |
| Product-Env-Stewards  | Product Envi   | Product Enviro Compliance |                             |                      | NA                            |   |                       |                                 |                                 | Product-Env-Stewards@onsemi.com       |                           |                     |                          |                                  |                                    |
| Authorized Representative*                                    |  |                           | Title - Representative      |                      |                               | Phone - Representative*   |                       |                                 |                                 | Email - Representative*               |                           |                     |                          |                                  |                                    |
| Product-Env-Stewards  | Product Enviro Compliance  |                           |                             |                      | NA                            |   |                       |                                 | Product-Env-Stewards@onsemi.com |                                       |                           |                     |                          |                                  |                                    |
| Requester Item Number   | Mfr Item Number  |                           | Number Mfr Item Name        |                      |                               |   | ective Date Version   |                                 | Manufacturing Site              |                                       | ,                         | Weight*             | k                        | UOM                              | Unit Type                          |
|   | MC74VI   | IC74DTG                   | LOG CMOS D FLIP FLOP        |                      |                               | 2024-05-09  | ,                     |                                 | PH1                             | PH1                                   |                           | 45.24               |                          | mg                               | Each                               |
| Manufacturing Proccess Informatio                             | n  |                           |                             |                      |                               |   |                       |                                 |                                 |                                       |                           |                     |                          |                                  | -                                  |
| Terminal Plating / Grid Array Mater                           | ial T  | erminal Base A            | Alloy                       | J-STD-020 MSL Rating |                               | Peak Process Bo   |                       | ody Temperat                    | Temperature Max Time at Peak    |                                       | Temperature Numbe         |                     | umber of                 | f Reflow Cycl                    | es                                 |
| Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)                   |  | U Alloy 1                 |                             | 1                    |                               | 260   |                       | C                               | 30                              |                                       | secon                     | seconds 3           |                          |                                  |                                    |
| Comments  |  |                           |                             |                      |                               |   |                       |                                 |                                 |                                       |                           |                     |                          |                                  |                                    |
| evel 1 - maximum time at peak temperature                     | during sol   | dering is 10-3            | 0 seconds                   |                      |                               |   |                       |                                 |                                 |                                       |                           |                     |                          |                                  |                                    |
| or more information regarding material co                     | nposition  | please refer to           | page 3                      |                      |                               |   |                       |                                 |                                 |                                       |                           |                     |                          |                                  |                                    |

| RoHS Material Composition Declaration  |  |  |   | Declaration Type *                              | Detailed  |  |  |  |  |  |  |
|--|--|--|---|---|---|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP). |  |   |   |   |  |  |  |  |  |  |
| cadmium, hexavalentchromium, polybrominate<br>contains a RoHS restricted substance inexcess<br>encompass all such components. Supplier certif<br>as of the date that Supplier completes this form<br>Company acknowledges that Supplier may hav<br>independently verified information provided by<br>certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip<br>of an applicable quantity limit, please ir<br>ies that it gathered the information it pro-<br>.Supplier acknowledges that Company<br>e relied on informationprovided by othe<br>v others, Supplier agrees that, at a minin<br>and the Supplier enter into a written agre<br>pource of the Supplier's liability and the   | henyl ethers (each a "<br>ndicate below which, i<br>ovides in this form us<br>will rely on this certifiers<br>in completing this<br>num, itssuppliers have<br>eement with respect to<br>Company's remedies | RoHS restricted substance") in exce<br>if any, RoHS exemption you believe<br>ing appropriate methods to ensure if<br>ication in determining the complian<br>form, and that Supplier may not have<br>e provided certifications regarding the<br>to the identified part, the terms and co<br>for issues that arise regarding inform | ce of its products with European Union membe    | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>l correct to the best of its knowledge and belief,<br>r state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>tions are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |  |
| RoHS Declaration * 1 - Item(s)   | does not contain RoHS restricted substa  | on above   | Supplier Acceptance   | * Accepted                                      |   |  |  |  |  |  |  |
| Exemption: If the declared item does not con applicable exemptions.  | ntain RoHS restricted substances per   | the definition above   | except for defined RoHS exempti   | ons, then select the corresponding response i   | n the RoHS Declaration above and choose all   |  |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU   |  |   |   |   |  |  |  |  |  |  |
| Declaration Signature  |  |  |   |   |   |  |  |  |  |  |  |
| Instructions: Complete all of the required fin<br>Requester) and click on Submit Form to have  | elds on all pages of this form. Select the form returned to the Requester  | he "Accepted" on th  | e Supplier Acceptance drop-down   | . This will display the signature area. Digital | lly sign the declaration (if required by the  |  |  |  |  |  |  |
| Supplier Digital Signature Ra  | stislav Drska  | Le   |   |   |   |  |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level    | Substance                  | CAS              | Exempt | Weight  | Unit of Measure |  |
|----------------------|--------|-----------------|----------|----------------------------|------------------|--------|---------|-----------------|--|
| Die                  | 2.0    | mg              | Supplier | Silicon (Si)               | 7440-21-3        |        | 2       | mg              |  |
| Die Attach           | 1.44   | mg              | Supplier | Silver (Ag)                | 7440-22-4        |        | 1.08    | mg              |  |
|                      |        |                 | Supplier | Epoxy resins               | 129915-35-1      |        | 0.36    | mg              |  |
| Lead Frame           | 22.54  | mg              | Supplier | Iron (Fe)                  | 7439-89-6        |        | 0.4283  | mg              |  |
|                      |        |                 | Supplier | Copper (Cu)                | 7440-50-8        |        | 22.1117 | mg              |  |
| Mold Compound-Black  | 19.0   | mg              |          | Epoxy resin                | proprietary data |        | 0.95    | mg              |  |
|                      |        |                 | Supplier | Phenolic Resin             | Proprietary Data |        | 0.95    | mg              |  |
|                      |        |                 | Supplier | Ortho Cresol Novolac Resin | 29690-82-2       |        | 0.38    | mg              |  |
|                      |        |                 | Supplier | Carbon Black (C)           | 1333-86-4        |        | 0.095   | mg              |  |
|                      |        |                 | Supplier | Fused Silica (SiO2)        | 60676-86-0       |        | 16.625  | mg              |  |
| Plating              | 0.04   | mg              | Supplier | Palladium (Pd)             | 7440-05-3        |        | 0.003   | mg              |  |
|                      |        |                 | В        | Nickel (Ni)                | 7440-02-0        |        | 0.0364  | mg              |  |
|                      |        |                 | Supplier | Gold (Au)                  | 7440-57-5        |        | 0.0006  | mg              |  |
| Wire Bond - Au       | 0.22   | mg              | Supplier | Gold (Au)                  | 7440-57-5        |        | 0.22    | mg              |  |